

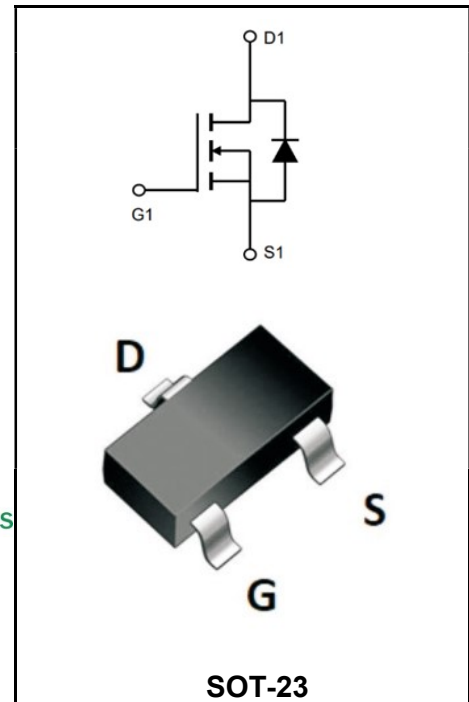
60V N-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

I_D	3A
V_{DSS}	60V
$R_{DS(ON)-typ}(@V_{GS}=10V)$	<100mΩ (Type:80mΩ)

Features

- ◆ Adopt advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.
- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply



Mechanical Data

- ◆ Case: Molded plastic
- ◆ Mounting Position: Any
- ◆ Molded Plastic: UL Flammability Classification Rating 94V-0
- ◆ Solder bath temperature 275°C maximum, 10s per JESD22-106

Product Specification Classification

Part Number	Part Number	Marking	Pack
YFW3N06	SOT-23	6003	3000PCS/Tape

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	VDS	60	V
Gate-Source Voltage	VGS	±20	V
Continue Drain Current @TA=25°C	ID	3.0	A
@TA=70°C		1.8	
Pulsed Drain Current (Note1)	IDM	9.2	A
Power Dissipation(TA = 25°C)	PD	1	W
Operating Temperature Range	TJ	-50 to +150	°C
Storage Temperature Range	TSTG	-50 to +150	°C
Thermal Resistance, Junction to Case	RθJC	80	°C/W
Thermal Resistance, Junction to Ambient	RθJA	125	°C/W

Electrical Characteristics at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	BV_{DSS}	60	-	-	V
Temperature Coefficient	Reference to 25°C , $I_D = 1\text{mA}$	BV_{DSS}	-	0.054	-	V/°C
Drain-Source On-State Resistance	$V_{GS} = 10\text{ V}, I_D = 2\text{ A}$	R_{DS(on)}	-	80	100	mΩ
	$V_{GS} = 4.5\text{ V}, I_D = 1\text{ A}$		-	85	110	
Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	V_{GS(th)}	1.2	-	2.5	V
Temperature Coefficient			-	-4.96	-	mV/°C
Drain-Source Leakage Current $T_J = 25^\circ\text{C}$	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$	I_{DSS}	-	-	1	uA
	$T_J = 55^\circ\text{C}$ $V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$		-	-	5	
Gate Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{V}$	I_{GSS}	-	-	±100	nA
Forward Transconductance	$V_{DS} = 5\text{V}, I_D = 2\text{A}$	g_{fs}	-	13	-	S
Total Gate Charge(4.5V)	$I_D = 2\text{ A}, V_{DS} = 48\text{ V}, V_{GS} = 4.5\text{ V}$	Q_G	-	5	7.0	nC
Gate to Source Charge		Q_{GS}	-	1.68	2.4	
Gate to Drain Charge		Q_{GD}	-	1.9	2.7	
Turn-on Delay Time(Note2)	$I_D = 2\text{ A}, V_{DD} = 30\text{ V}, R_G = 3.3, V_{GS} = 10\text{V}$	t_{d(ON)}	-	1.6	3.2	nS
Rise Time(Note2)		tr	-	7.2	13	
Turn-Off Delay Time(Note2)		t_{d(OFF)}	-	25	50	
Fall Time(Note2)		t_f	-	14.4	28.8	
Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 15\text{ V}, f = 1\text{MHz}$	C_{iss}	-	511	715	pF
Output Capacitance		C_{OSS}	-	38	53	
Reverse Transfer Capacitance		C_{rss}	-	25	35	

Source-Drain Diode Characteristics at Ta=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min.	Typ.	Max.	Unit
Maximun Body-Diode Continuous Current	V _G =V _D =0V , Force Curren	I _S	-	-	2.3	A
Maximun Body-Diode Pulsed Current		I _{SM}	-	-	9.2	A
Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 1 A, T _J =25°C	V _{SD}	-	-	1.2	V
Reverse Recovery Time	I _F = 2 A, diF/dt =100A /μs, T _J =25°C	t _{rr}	-	9.7	-	nS
Reverse Recovery Charge		Q _{rr}	-	5.8	-	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3.The power dissipation is limited by 150°C junction temperature.
- 4.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

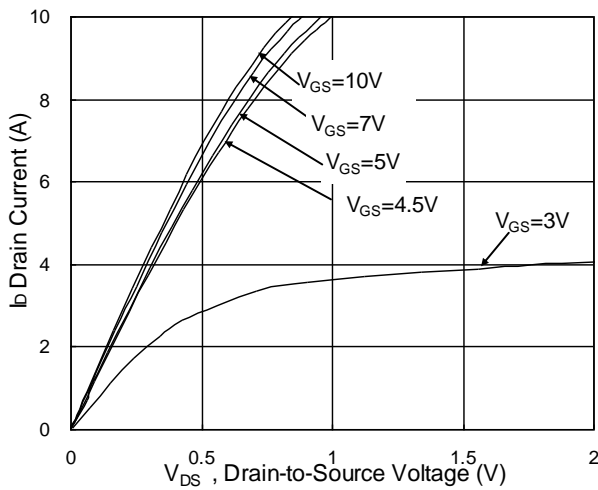


Fig.1 Typical Output Characteristics

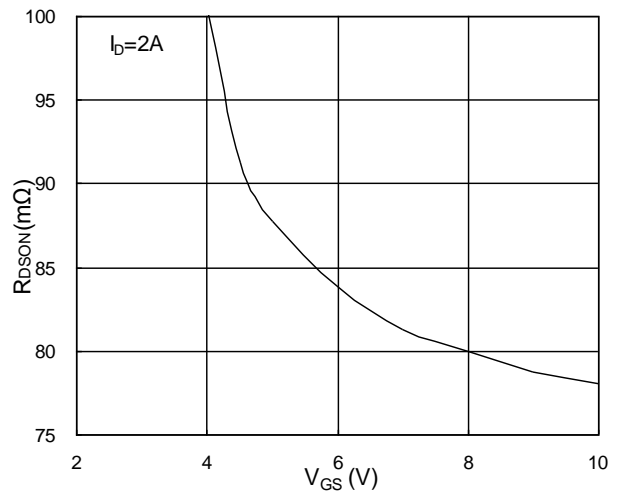


Fig.2 On-Resistance v.s Gate-Source

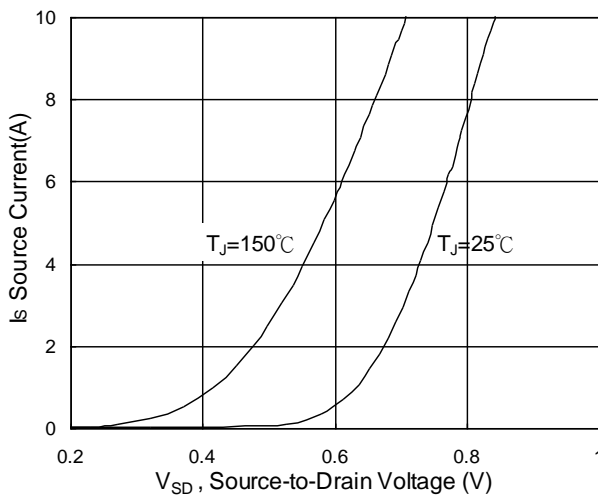


Fig.3 Forward Characteristics of Reverse

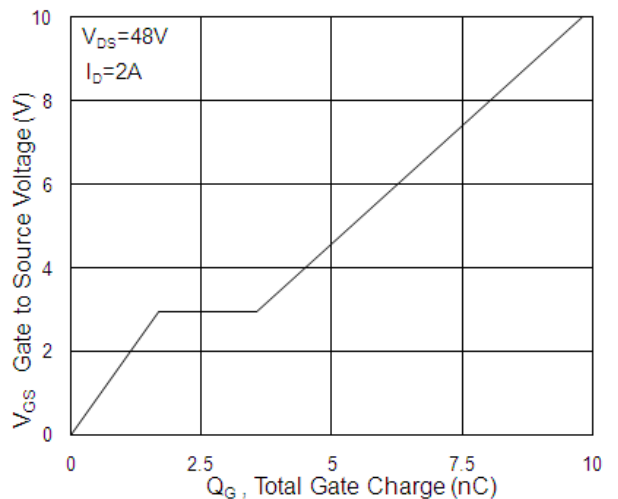


Fig.4 Gate-Charge Characteristics

Ratings and Characteristic Curves

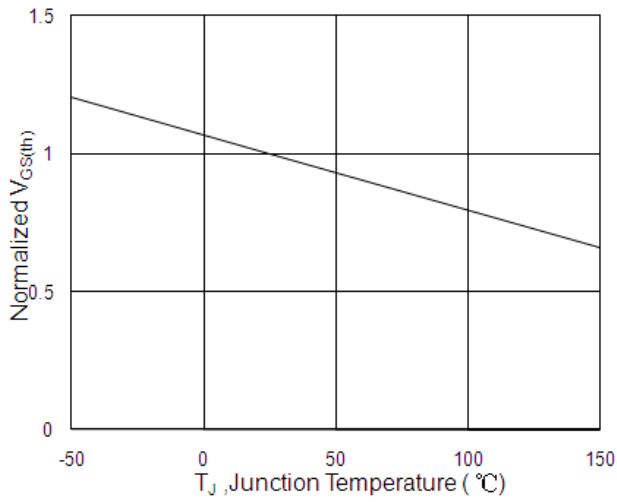


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

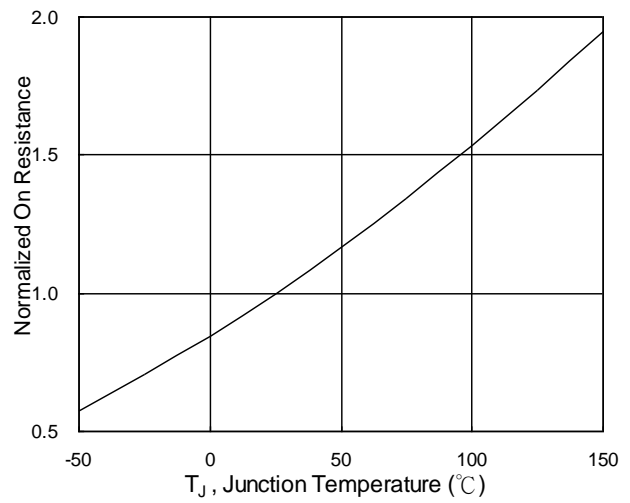


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

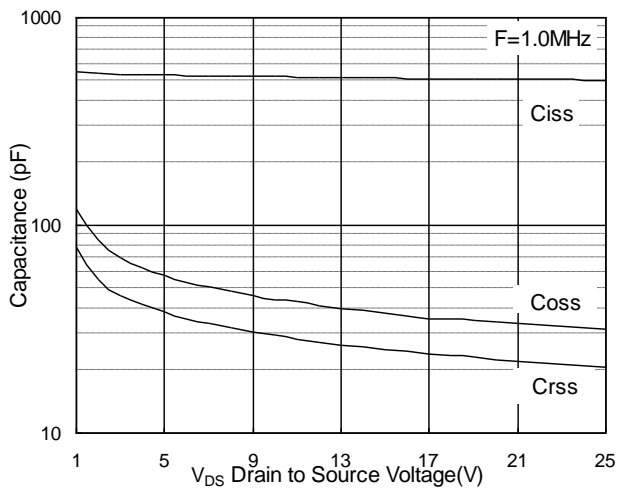


Fig.7 Capacitance

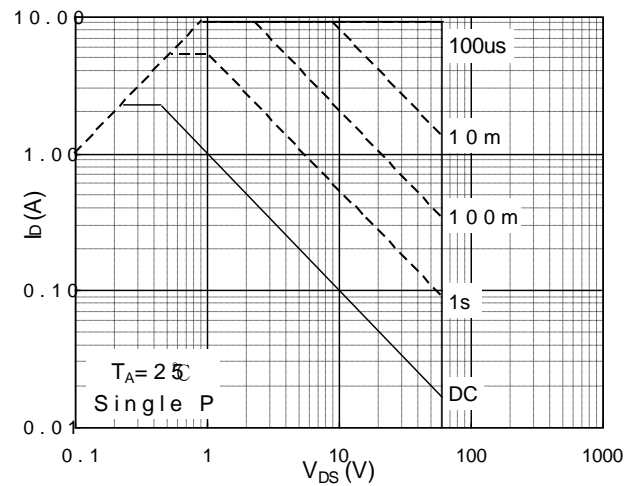


Fig.8 Safe Operating Area

Ratings and Characteristic Curves

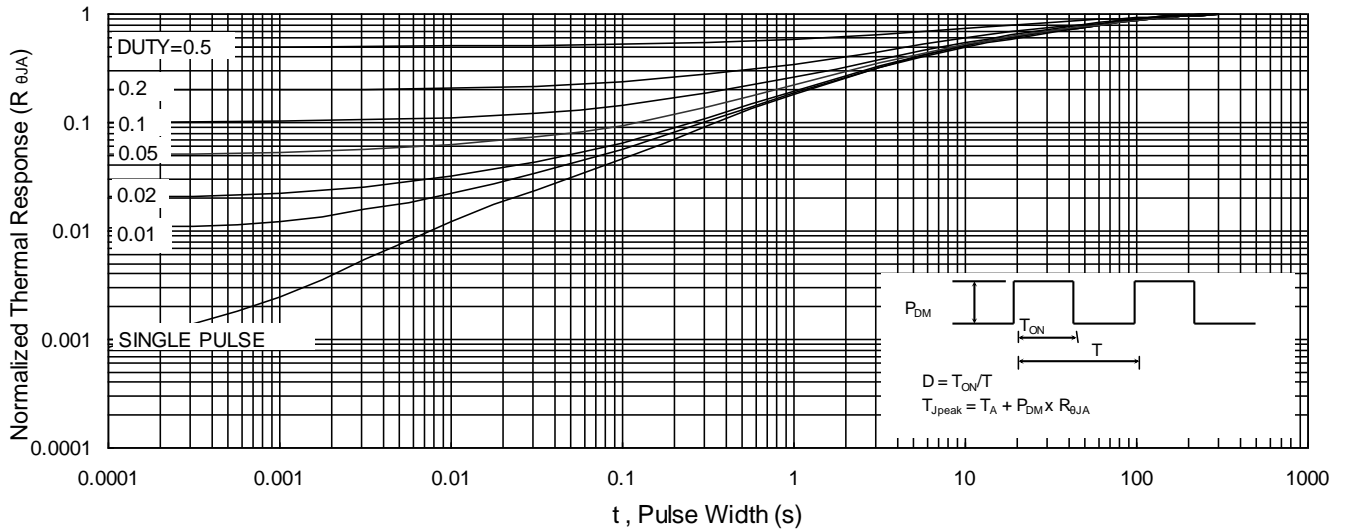


Fig.9 Normalized Maximum Transient Thermal Impedance

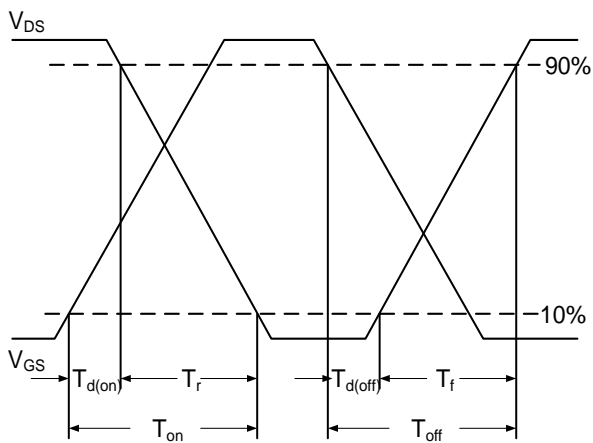


Fig.10 Switching Time Waveform

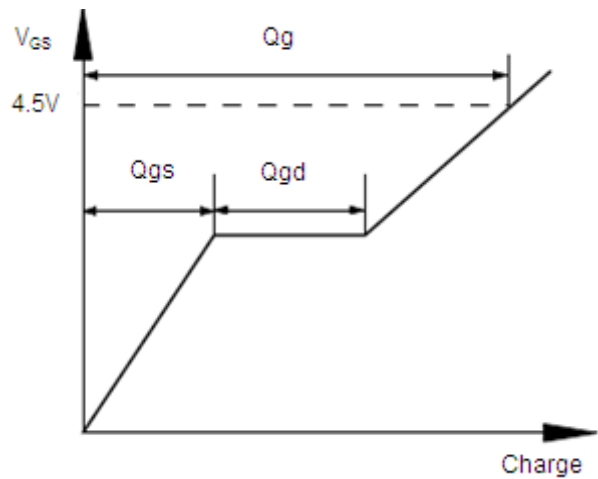
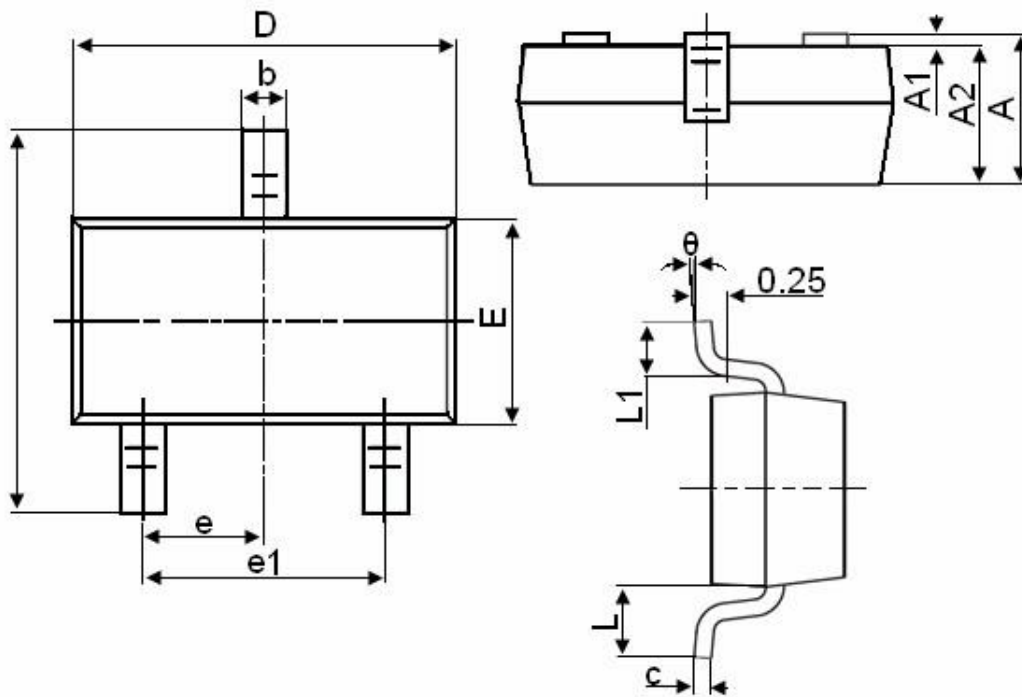


Fig.11 Gate Charge Waveform



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°